1. Built on PMP20777PCB Rev A.
2. C100, C101, R100 and R101 were added for Rev B.
3. L1 was removed and shorted.
4. T1 pin 1 marking in wrong location on PCB.

Assembly Notes:

- VIN = 36 - 72V
- UVLO Set Point = 35.875V
- Fsw = 100 kHz
- Current Transfer Ratio = 80 - 160%
- 250 LFM Air Flow Required if Extended Operation at Full Load

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